Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package name	Standard dimensions mm (inch)	Not Mounted
1	CN1	1	–	XG8W-1431	Omron	Terminal, 300 V, 3 A	–	–	
2	CN2	1	–	XG4C-1631	Omron	Terminal, 250 V, 1 A	–	–	
3	CN3	1	–	WR-60P-HF-HD-A1E	JAE	Terminal, 200 V, 0.3 A	–	–	
4	CN4	1	–	SM03B-PASS-TBT(LF)(SN)	JST	Terminal, 250 V, 3 A	–	–	
5	CN5	1	–	SM02B-PASS-TBT(LF)(SN)	JST	Terminal, 250 V, 3 A	–	–	
6	CN6	1	–	SM04B-PASS-TBT(LF)(SN)	JST	Terminal, 250 V, 3 A	–	–	
7	CN7	1	–	SM10B-PASS-TBT(LF)(SN)	JST	Terminal, 250 V, 3 A	–	–	
8	C1, C5, C6, C7, C17, C83	6	0.1 µF			Ceramic, 6.3 V, ±15 %	1005	1.0 x 0.5 (0402)	
9	C2, C4	2	1000 pF			Ceramic, 16 V, ±15 %	1608	1.6 x 0.8 (0603)	
10	C8, C9, C10, C11, C12, C13, C14, C15, C16, C18, C20, C21, C22, C23, C24, C25, C26, C27, C28, C29, C30, C31, C32, C33, C34, C35, C36, C37, C38, C39, C40, C41, C42, C43, C44, C45, C46, C47, C48, C49, C50, C51, C52, C53, C85, C86, C89, C90, C96,C97	50	1 µF			Ceramic, 10 V, ±10 %	1608	1.6 x 0.8 (0603)	
11	C19, C79, C81, C82, C84, C87, C88, C92, C93, C94	10	10 µF			Ceramic, 10 V, ±10 %	1608	1.6 x 0.8 (0603)	
12	C54, C55, C56, C57, C60, C69, C76, C77, C78, C80, C91, C95	12	0.1 µF			Ceramic, 50 V, ±10 %	1608	1.6 x 0.8 (0603)	
13	C58, C59, C61, C62, C67, C68, C70, C71	8	470 pF			Ceramic, 50 V, ±5 %	1608	1.6 x 0.8 (0603)	

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package name	Standard dimensions mm (inch)	Not Mounted
14	C63, C64, C65, C66, C72, C73, C74, C75	8	0.015 µF			Ceramic, 50 V, ±10 %	1608	1.6 x 0.8 (0603)	
15	D1, D2, D3, D4, D5, D7, D8, D9, D10, D11, D12, D13, D14, D15, D16, D17, D18, D19, D20, D21, D22, D23, D24	23	45 V	1SS396	TOSHIBA	Schottky Barrier Diode	SOT-346	2.9 x 2.5	
16	D6	1	30 V	CUS05F30	TOSHIBA	Schottky Barrier Diode	SOD-323	2.5 x 1.25	
17	FU1, FU2	2	1.6 A			Fuse	–	6.0 x 2.5	
18	IC1, IC2	2	–	TPS3897ADRY	Texas Instruments	Adjustable Voltage Monitor	SON	1.2 x 1.65	
19	IC3	1	–	TMS320F28377SPTP	Texas Instruments	32-bit Microcontrollers-MCU Soprano	HLQFP	24 x 24	
20	IC4	1	512 Kbit	24LC512-I/SM	Atmel	EEPROM	SOIJ	5.21 x 5.28	
21	IC5, IC6, IC7	3	–	74VHCT540AFT	TOSHIBA	Buffer	TSSOP 20B	6.5 x 6.4	
22	IC8, IC13, IC14	3	–	TC7SH17F	TOSHIBA	Single Schmitt Buffer	SOT-25	2.9×2.8	
23	IC9, IC10	2	–	OPA4322AIPWR	Texas Instruments	Operational amplifier	TSSOP-14	6.9×5.6	
24	IC11	1	–	TC74VHC540FT	TOSHIBA	Buffer	TSSOP	6.9 x 4.4	
25	IC12	1	–	TCAN332D	Texas Instruments	CAN Transceivers	SOIC	5.0 x 3.9	
26	IC15	1	–	REF2030AIDDCT	Texas Instruments	Voltage References	SOT-23-THIN	3.05 x 3.05	
27	LED1	1	–	VCDG1111C-4BY3C-TR	STANLEY	LED	TSSOP 20B	6.5 x 6.4	
28	L1	1	–	MMZ2012S601AT000	TDK	Chip beads	2012	2.0 x 1.2 (0805)	
29	PS1	1	3.3 V 1.5 A	TCR15AG33	TOSHIBA	Regulator	WCSP6F	1.2 x 0.8	
30	PS2	1	1.2 V 1.5 A	TCR15AG12	TOSHIBA	Regulator	WCSP6F	1.2 x 0.8	
31	R1 ,R12, R13, R20, R21	5	4.7 kΩ			100 mW, ±1 %	1608	1.6 x 0.8 (0603)	
32	R2	1	300 kΩ			100 mW, ±0.1 %	1608	1.6 x 0.8 (0603)	
33	R3, R17, R22, R23, R24, R25, R26	7	100 kΩ			100 mW, ±1 %	1608	1.6 x 0.8 (0603)	
34	R4	1	56 kΩ			100 mW, ±0.1 %	1608	1.6 x 0.8 (0603)	

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package name	Standard dimensions mm (inch)	Not Mounted
35	R5, R7, R15, R16, R30, R31, R32, R33, R34, R35, R36, R37, R38, R39, R40, R41, R42, R43, R44, R45, R46, R47, R48, R49, R50, R51, R54, R55, R62, R63, R66, R67, R74, R75, R76, R77, R78, R79, R80, R82, R83, R84, R86, R88, R89, R90, R91, R92, R93, R94, R95	51	10 kΩ			100 mW, ±1 %	1608	1.6 x 0.8 (0603)	
36	R6	1	130 kΩ			100 mW, ±1 %	1608	1.6 x 0.8 (0603)	
37	R11, R85, R87, R96, R97, R98, R99, R100, R101, R102, R103	11	100 Ω			100 mW, ±1 %	1608	1.6 x 0.8 (0603)	
38	R14, R28, R29	3	2.2 kΩ			100 mW, ±1 %	1608	1.6 x 0.8 (0603)	
39	R18	1	0 Ω			1 A	1608	1.6 x 0.8 (0603)	
40	R52, R53, R56, R57, R64, R65, R68, R69	8	15 kΩ			100 mW, ±1 %	1608	1.6 x 0.8 (0603)	
41	R58, R59, R60, R61, R70, R71, R72, R73	8	33 Ω			100 mW, ±1 %	1608	1.6 x 0.8 (0603)	
42	R81	1	470 Ω			100 mW, ±1 %	1608	1.6 x 0.8 (0603)	
43	SW1	1	–	SKRKAEE010	ALPS	Tact Switch	-	4.8 x 2.9	
44	SW2	1	–	A6H-2102	Omron	Slide DIP Switch	-	3.77 x 4.5	
45	TP1, TP2, TP3, TP4, TP5, TP6, TP7, TP8, TP9, TP10, TP11, TP12, TP13, TP14, TP24, TP25	16	–	HK-3-G	MAC8	Test Pin	-	2.0 x 1.3	

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package name	Standard dimensions mm (inch)	Not Mounted
46	X1	1	–	ASEMB-20.000MHZ-XY-T	Abracon	Clock Oscillators	QFN	3.2 x 2.5	
901	C3	1	–	–	–	–	1608	1.6 x 0.8 (0603)	Not Mounted
902	R8, R9, R10, R19	4	–	–	–	–	1608	1.6 x 0.8 (0603)	Not Mounted

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